

IPC-2591-Version 1.2

2020 - September

Connected Factory Exchange (CFX)

An international standard developed by IPC



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- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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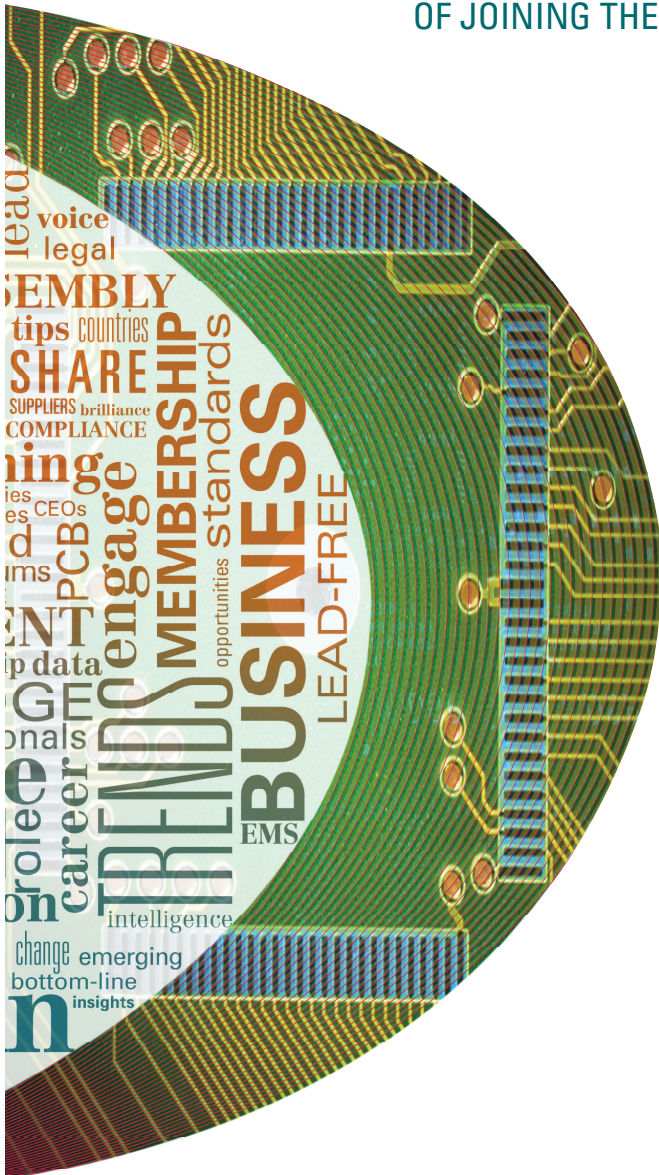


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Connected Factory Exchange (CFX)

Developed by the Connected Factory Initiative Subcommittee (2-17) and the Connected Factory Initiative Subcommittee – China (2-17CN) of the Electronic Product Data Description Committee (2-10) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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